



Technical Data Sheet
HYSOL GR 2310

1048230
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PRODUCT DESCRIPTION

HYSOL GR 2310 is a green, semiconductor grade mold compound providing the following product characteristics:

Technology	Epoxy
Cure	Heat cure
Appearance	Golden
Product Benefits	<ul style="list-style-type: none">• Optimum performance• Low moisture absorption• Good moldability• Fast cycle time• Lasermark capability• Low ionic impurities Excellent thermal cycling performance
Filler Weight, %	72
Target Package	Tantalum capacitor and leaded or surface-mounted sensors
Application	Mold Compound
Flammability	UL 94 V0

HYSOL GR 2310 epoxy molding compound delivers outstanding performance and ease of use.

HYSOL GR 2310 meets UL 94 V-0 Flammability at 6.35mm thickness.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Spiral Flow, @175°C, cm	72
Gel Time, @175°C, seconds	12
Shelf Life, @ 5°C, days	365

TYPICAL PROCESS DATA

Handling	Typical Value
Preheat Temperature, °C	80~95
Molding Temperature, °C	140-180
Transfer Pressure, Kg/cm ²	40~85
Transfer Time, seconds	6~15
Curing Time	
Conventional mold @ 175°C, seconds	70~90
Auto mold @ 175°C, seconds	50~70
Post Mold Cure @ 175 °C, hours	4~8

HYSOL GR 510-HP has been formulated to provide the best possible moldability and as wide a molding latitude as possible. Although molding and curing conditions will vary from situation to situation, recommended starting ranges are shown above.

Please contact Hysol Huawei Technical Service for alternative process parameters if needed.

TYPICAL PROPERTIES OF CURED MATERIAL

All measurements are taken at 25°C unless otherwise noted.

All physical, electrical and analytical measurements are taken on specimens cured for **120** seconds @ **175°C** with post cure of 6 hours @ **175°C**, unless otherwise specified.

Physical Properties

Property	Typical Value
Glass Transition Temperature, °C:	175
Coefficient of Thermal Expansion, TMA, ppm/°C:	
Below Tg	20
Above Tg	73
Specific Gravity	1.82
Molded Shrinkage, as molded, %	0.28
Flexural Modulus @ 25°C	1.8 × 10 ⁶ psi
Flexural Strength @ 25°C	17,300 psi
Thermal Conductivity, W/(m-K)	0.64
Water Extract Data, 20 hours water boil:	
Conductivity, µmhos/cm	24
pH of extract	6.0
Extractable Ionic Content, ppm:	
Chloride (Cl-)	13
Sodium (Na+)	9

Electrical Properties

Volume Resistivity, ohms-cm, 500 volts:@25°C	20 × 10 ¹⁵
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GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

Not for product specifications

The technical data contained herein are intended as reference only. Please contact Hysol Huawei Electronics Co., Ltd. quality department for assistance and recommendations on specifications for this product

Storage

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: 5°C or below, in closed containers. After removal from cold storage, the material **MUST** be allowed to come to room temperature, in the sealed container, to avoid moisture contamination. The suggested waiting time for a standard 15 kg carton box is 24 hours.

Material removed from containers may be contaminated during use. Do not return product to the original container. Hysol Huawei Electronics Co., Ltd. cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please

contact Hysol Huawei Electronics Co., Ltd. Technical Service or Customer Service Representative.

Disclaimer

NOTE

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our best knowledge and experience of the product as at the date of this TDS. Hysol Huawei Electronics Co., Ltd. is, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

Any liability in respect of the information in the Technical Data Sheet regarding the concerned product is excluded.